

Title (en)

Method for the electrolytic deposition of copper

Title (de)

Verfahren zur elektrolytischen Abscheidung von Kupfer

Title (fr)

Procédé pour la déposition électrolytique de cuivre

Publication

**EP 1630258 A1 20060301 (DE)**

Application

**EP 05018241 A 20050823**

Priority

DE 102004041701 A 20040828

Abstract (en)

The flow rate of the electrolyte of the matting process is significantly increased by treating with an electrolyte containing copper in an acid (Copper alkydsulphate).

IPC 8 full level

**C25D 3/38** (2006.01)

CPC (source: EP US)

**C25D 3/38** (2013.01 - EP US)

Citation (search report)

- [XA] EP 1408141 A1 20040414 - ENTHONE [US]
- [XA] US 6676823 B1 20040113 - BOKISA GEORGE [US]
- [XA] US 6491806 B1 20021210 - DUBIN VALERY [US], et al
- [A] US 4036711 A 19770719 - KARDOS OTTO, et al
- [A] US 4134803 A 19790116 - ECKLES WILLIAM E, et al

Designated contracting state (EPC)

DE ES FR GB NL

DOCDB simple family (publication)

**EP 1630258 A1 20060301; EP 1630258 B1 20130227**; CN 1740399 A 20060301; DE 102004041701 A1 20060302; ES 2402688 T3 20130507; JP 2006063450 A 20060309; JP 4283256 B2 20090624; US 2006049058 A1 20060309

DOCDB simple family (application)

**EP 05018241 A 20050823**; CN 200510092292 A 20050826; DE 102004041701 A 20040828; ES 05018241 T 20050823; JP 2005243009 A 20050824; US 21442105 A 20050829